

Description

Background of the Invention

This invention relates, in general, to a method for trimming an electrical component that is located within an integrated circuit and, more particularly, to a method for trimming implanted or diffused resistors by the use of metal migration.

The term "trimming" is used to mean the fine adjustment of resistance, capacitance, or inductance in a circuit. As used herein, "metal migration" refers to the movement of metal into a semiconductor crystal (e.g. a resistor). This movement of metal is caused by sending current pulses through the resistor. These pulses are usually of high amplitude and small pulse width.

In the manufacture and packaging of integrated circuits, it is sometimes necessary to "match" (make electrically identical) resistors, transistors, diodes or to set the absolute value of a single electronic device to a certain value, such as trimming a resistor to set a particular current level. For example, trimming of component values on an integrated circuit chip can result in minimizing the input offset voltage of an operational amplifier, or its temperature coefficient of input offset voltage. Trimming of a voltage reference can set the output voltage and temperature coefficient to precise values. Trimming of D/A or A/D converters is commonly done in order to obtain increased accuracy.

Resistor trimming is by far the most common means of adjusting electrical parameters of integrated circuits. Two methods are generally used. The first is to use a trim potentiometer outside the semiconductor device but connected to it through external pins, i.e. on a printed circuit board. The second method is to trim a resistor on the integrated circuit die itself.

In the prior art, electronic components, eg. resistors, have been trimmed by mechanical, electrical, or chemical means. For example, mechanical means include abrasion, usually by sandblasting, and laser shaping of a conductive layer. Electrical means include fuse blowing, i.e. vaporization of metal by passing high current therethrough and short-circuiting diodes with excessive current. The latter is also known as "zener zapping" since the diodes connected along the resistive elements are zener diodes. Chemically changing the conductivity of the resistor by anodizing the metal is possible but not often used in a production environment.

The known methods of resistor trimming on the die have serious disadvantages. The cost of laser trimming equipment is high. The maintenance and programming of such equipment are extremely critical and costly. Fuse blowing can cause surface contamination and cracks in the protective glass layer which, in turn, cause reliability problems. Zener zapping can require

that over twenty per cent of the die be dedicated to resistor trimming.

A further advantage in the known methods of resistor trimming on the die is that after the die is trimmed (usually in wafer form) it is scribed and assembled in a package. This assembly process can put stress on the semiconductor chip which can cause the trimmed resistor to change due to piezoresistive effects. It would, therefore, be advantageous to be able to trim an on chip resistor after the integrated circuit die is in the package.

Summary of the Invention

It is an object of this invention to provide a method for adjusting the value of a resistive device located within an integrated circuit by the use of the phenomenon known as metal migration.

Another object of the present invention is to reduce the amount of circuitry that is needed to trim a resistor.

A further object of the present invention is to be able to trim resistors after the die has been sealed in the package.

According to an aspect of the invention there is provided a method for trimming the values of a resistive device located within an integrated circuit comprising the steps of:

forming metal contact regions at least at each end of the resistive device, each metal contact region having mirror apexes pointing at each other, which apexes are much smaller relative to the size of the metal contact region to facilitate migration of metal from one of said apexes toward the other;

providing a pulsating electrical current which flows through the resistive device in a single direction only, said electrical current being sufficient to cause a metal filament to migrate from said one apex of said metal contact region toward the other metal contact region; and

terminating said electrical current after a predetermined length of time.

According to a further aspect of the invention there is provided a resistive device formed on a substrate, comprising:

a first metal contact region at one end of said resistive device; and

a second metal contact region at an opposite end of said resistive device, said first and second metal contact regions having mirror apexes pointing at each other, which apexes are much smaller relative to the size of the metal contact region to facilitate movement of a metal filament from one of said apexes toward the other.

A more complete understanding of the present invention can be attained by considering the following detailed description in conjunction with the accompanying drawings.

Brief Description of the Drawings

FIG. 1 is a schematic diagram of a typical J-FET operational amplifier in which the present invention can be used.

FIG. 2 illustrates a sectional side view of a resistor.

FIG. 3 illustrates the top view of the resistor of FIG. 2.

FIG. 4 illustrates a sectional side view of a resistor with additional metal contacts.

FIG. 5 illustrates the top view of the resistor of FIG. 4.

FIGS. 6-8 illustrate the top view of a resistor with alternate geometric contacts.

Detailed Description of the Invention

It is well known in the art that a resistor is constructed on an integrated circuit by implanting or diffusing dopants into a semiconductor material through apertures in a masking material. The contacts are formed by depositing an insulating layer over the resistor region. Openings, called preohmics, are etched into the insulating layer at each end of the resistor. A layer of metal is deposited over the insulating layer and into the preohmics, thus making contacts with the resistor. The shape of the preohmic defines the shape of the metal contact.

Pulsating a direct current through the metal contacts of the diffused resistor results in a metal filament controllably migrating from the positive contact to the negative contact. As the metal migrates through the silicon, the value of the resistor changes. A contact with a sharp corner or a corner with a small radius of curvature will allow the metal to migrate with less current than, for example, a circular contact with a large radius.

The term "contact" refers to the metal region touching the resistor region. The geometric metal contacts located on each end of the resistor are also identified as "primary contacts" since they are the ones through which current is supplied. As is more clear from the detailed description herein, additional or secondary contacts are located intermediate the primary contacts. These are not used for supplying current, but merely respond to the current flowing between the primary contacts.

The secondary contacts and the positive primary contact migrate metal at the same time if all the preohmics have the same radius of curvature at the point where the metal begins to migrate. This is important because it defines the geometry of the filament, which is necessary for long term stability of the resistor.

It also has been determined that the geometry of the filament will be determined by the direction of the resistor relative to the crystallographic planes in the wafer substrate, and by the direction of current flow in the resistor.

FIG. 1 illustrates a portion of a typical operational amplifier within which trimming resistors are used. Trimming resistors can also be found in regular multipliers, and filters, among other applications. Thus, the circuit of FIG. 1 is repre-

sentative and not exhaustive of the uses of the present invention.

Current source is connected to the sources of transistors 12 and 13. Bonding pads 16 and 17 are connected to transistors 12 and 13 by way of gate terminals 14 and 15, respectively. The bases of transistors 18 and 19 are connected to nodes 20 and 21 respectively. Nodes 20 and 21 are located between the drains of transistors 12 and 13 and the collectors of transistors 22 and 23 respectively. Node 24 is located between the base of transistor 22 and the base of transistor 23. The emitter of transistor 18 is connected to node 24. The collectors of transistors 18 and 19 are connected to a suitable power supply illustrated as V_{cc} . The emitter of transistor 19 is connected to the next stage in the amplifier, not shown. The emitters of transistors 22 and 23 are connected to nodes 38 and 39, respectively. Diode 28 is connected to node 38 and diode 25 is connected to node 39. Diode 28 and 25 are grounded. Nodes 38 and 39 are connected to resistors 26 and 27, respectively. Resistor 26, pad 30 and resistor 32 are connected to node 37. Resistor 27, pad 31, and resistor 33 are connected to node 29. Resistor 32 and 33 are connected to nodes 34 and 35 respectively. Nodes 34 and 35 are connected to ground pad 36.

The operation of such amplifiers is well known per se in the art and will only be discussed in detail in connection with the trimming of resistors 32 and 33.

FIG. 2 is a sectional view of the various layers that make up a diffused resistor. In this embodiment, substrate 41 comprises a P-type silicon layer covered by an N-type epitaxial layer 42. Resistor 43 comprises an N-type dopant that is diffused into epitaxial layer 42. Insulating layer 44 preferably comprises nitride, although other insulators could be used, and is deposited over the epitaxial layer 42. Openings 45 are etched into nitride layer 44. Metal layer 46 is deposited over the nitride layer and in openings 45, thus creating metal contacts 50 and 51 (FIG. 3). Protective glass layer 47 is deposited over the metal, and openings 48 and 52 are etched into glass layer 47 to provide access to pads 53 and 54. FIG. 3 does not show the protective glass layer.

When a pulsating current is connected across pads 53 and 54, the metal begins to migrate from metal contact 50, in resistor 43, towards metal contact 51 as represented by region 49. Typical values for current are 250 to 300 milliamps with a range of 250 to 650 milliamps, depending on the resistor characteristics. This current is far in excess of the current flowing through the resistor during normal operation of the amplifier, eg. 100 milliamperes. The metal migrates as shown by 49 in the same direction as hole flow and opposite to electron flow. In FIG. 3, pad 53 is connected to a positive voltage source and pad 54 is connected to a negative voltage source or ground. A resistor is trimmed to a given value by adjusting the duration and amount of current passing through it as well as by adjusting the number of current

pulses. It is possible to completely short the resistor by pulsing the current for an extended length of time.

While suitable in many applications, the embodiment of FIGS. 2 and 3 is more suited to small changes in resistance. If region 49 is caused to grow significantly, eg. greater than the size of the primary contact as measured in the same direction, then some drift may be encountered in operation of the device. To correct for the drifting value, a further embodiment of this invention is shown in FIGS. 4 and 5.

In this embodiment, a plurality of secondary contacts are added so that the migration is spread over several regions located more or less along a straight line between the primary contacts. Substrate 41 is covered by epitaxial layer 42. Resistor 43 is diffused into epitaxial layer 42. Insulating layer 44 preferably comprises nitride, is located on top of the epitaxial layer. Openings 45 and 55 are etched into nitride layer 44. Openings 55 may have any shape and are merely illustrated as circular in shape. Metal 46 is deposited over the nitride and into 45 and 55, thus creating metal contacts 50, 51, and 56. Contacts are known as secondary contacts. Protective glass layer 47 is deposited over the metal, and openings 48 and 52 are etched into the glass to provide access to pads 53 and 54. FIG. 5 does not show the protective glass layer. Applying a pulsating current having a positive polarity at pad 53 and a negative polarity at pad 54 the metal begins to migrate from metal contact 50, toward metal contact 51 as illustrated by regions 49. Each of the circular metal contacts 56 has metal migrating toward contact 51. Less trim time is used with this embodiment thereby producing shorter dendrites or filaments of metal, which has been found to prevent the value of the resistor from drifting.

FIGS. 6-8 illustrate alternative embodiments of shapes for primary contacts 50 and 51. Secondary contacts may be added or not, as desired. The primary contacts are also characterized by mirrored apexes pointing at each other and having a radius of curvature which is small relative to the size of the contact.

A number of variations in the basic process are possible. Substrate 41 can be N-type and epitaxial layer 42 a P-type layer. Resistor 43 can be implanted and/or be P-type. Insulating layer 44 can comprise oxide or a combination of oxide and nitride or polyimide. Metal layer 46 can comprise pure aluminum, aluminum alloy such as aluminum copper, aluminum silicon, or aluminum copper silicon or other metal. The protective layer can comprise doped silicon dioxide, silicon nitride, plasma silicon, polyimide, or the like.

The advantages of resistor trimming by metal migration (RTMM) are numerous. Conventional processes and test equipment can be used to manufacture and trim the diffused RTMM resistor, unlike expensive thin film processes with laser trim. The migrating metal occurs in the silicon body of the RTMM resistor, which does not damage the protective passivation on the surface

of the I.C. chip. This is not the case with laser trim or fuse blowing techniques. For laser trimming elaborate test programs must be written to increment the laser to the proper targets. RTMM does not require this. Trimming by zener zapping requires complicated circuitry along with high voltage protection schemes. Also, it consumes typically twenty per cent of the total die area. Trimming with RTMM requires very little die area. Trimming with the RTMM resistor can be done after the I.C. chip is sealed in the package, which will trim out any inaccuracies caused by package stresses. Since RTMM is an analog trimming method, much more accuracy can be achieved with computer control than can be achieved by zener zapping on the die.

There is thus provided by the present invention an improved method for trimming resistors. It requires no special processing and produces more stable components.

Having thus described the invention, it will be apparent to those skilled in the art that various modifications can be made within the scope of the present invention. For example, while the pre ohmic holes are illustrated as uniformly spaced in Figures 4 and 5, they need not be. Also, as previously discussed, the present invention can be implemented in a variety of semiconductor materials and conductivity types.

Claims

1. A method for trimming the values of a resistive device located within an integrated circuit comprising the steps of:

forming metal contact regions at least at each end of the resistive device, each metal contact region having mirror apexes pointing at each other, which apexes are much smaller relative to the size of the metal contact region to facilitate migration of metal from one of said apexes toward the other;

providing a pulsating electrical current which flows through the resistive device in a single direction only, said electrical current being sufficient to cause a metal filament to migrate from said one apex of said metal contact region toward the other metal contact region; and

terminating said electrical current after a predetermined length of time.

2. The method of claim 1 further comprising forming a plurality of secondary contact regions within the resistive device between said metal contact regions, said secondary contact regions being separated from each other.

3. The method as defined in claim 1, in which said resistive device comprises a diffused resistor.

4. The method as defined in claim 1, in which said resistive device comprises an ion implanted resistor.

5. A resistive device formed on a substrate, comprising:

a first metal contact region at one end of said resistive device; and

a second metal contact region at an opposite

pulses. It is possible to completely short the resistor by pulsing the current for an extended length of time.

While suitable in many applications, the embodiment of FIGS. 2 and 3 is more suited to small changes in resistance. If region 49 is caused to grow significantly, eg. greater than the size of the primary contact as measured in the same direction, then some drift may be encountered in operation of the device. To correct for the drifting value, a further embodiment of this invention is shown in FIGS. 4 and 5.

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of the I.C. chip. This is not the case with laser trim or fuse blowing techniques. For laser trimming elaborate test programs must be written to increment the laser to the proper targets. RTMM does not require this. Trimming by zener zapping requires complicated circuitry along with high voltage protection schemes. Also, it consumes typically twenty per cent of the total die area. Trimming with RTMM requires very little die area. Trimming with the RTMM resistor can be done after the I.C. chip is sealed in the package, which will trim out any inaccuracies caused by packaging stresses. Since RTMM is an analog trimming method, much more accuracy can be achieved with computer control than can be achieved by zener zapping on the die.

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Claims

1. A method for trimming the values of a resistive device located within an integrated circuit comprising the steps of:

forming metal contact regions at least at each end of the resistive device, each metal contact region having mirror apexes pointing at each other, which apexes are much smaller relative to the size of the metal contact region to facilitate migration of metal from one of said apexes toward the other;

providing a pulsating electrical current which flows through the resistive device in a single direction only, said electrical current being sufficient to cause a metal filament to migrate from said one apex of said metal contact region toward the other metal contact region; and

terminating said electrical current after a predetermined length of time.

2. The method of claim 1 further comprising forming a plurality of secondary contact regions within the resistive device between said metal contact regions, said secondary contact regions being separated from each other.

3. The method as defined in claim 1, in which said resistive device comprises a diffused resistor.

4. The method as defined in claim 1, in which said resistive device comprises an ion implanted resistor.

5. A resistive device formed on a substrate comprising:

a first metal contact region at one end of said resistive device; and

a second metal contact region at an opposite



end of said resistive device, said first and second metal contact regions having mirror apexes pointing at each other, which apexes are much smaller relative to the size of the metal contact region to facilitate movement of a metal filament from one of said apexes toward the other.

6. The resistive device of claim 5 comprising a plurality of secondary metal contact regions within the resistive device between said first and second metal contact regions.

7. The resistive device of claim 5 comprising an ion implanted resistor.

8. The resistive device of claim 5 comprising a diffused resistor.

Patentansprüche

1. Verfahren zum Trimmen der Werte eines Widerstandsbauelementes in einer integrierten Schaltung, gekennzeichnet durch folgende Schritte:

Ausbilden von Metallkontaktbereichen wenigstens an jedem Ende des Widerstandsbauelementes, wobei alle Metallkontaktbereiche spiegelbildliche Spitzen haben, die aufeinander zu weisen und viel kleiner als die Metallkontaktbereiche sind, um die Migration des Metalls von einer Spitze in Richtung der anderen zu erleichtern,

Zuführen eines pulsierenden elektrischen Stromes, der nur in einer einzigen Richtung durch das Widerstandsbauelement fließt und ausreicht, daß ein Metallfaden von einer Spitze des Metallkontaktbereiches in Richtung des anderen Kontaktbereiches wandert, und Abschalten des elektrischen Stromes nach einer vorbestimmten Zeitspanne.

2. Verfahren nach Anspruch 1, ferner gekennzeichnet durch die Ausbildung mehrerer Sekundärkontaktbereiche in dem Widerstandsbauelement zwischen den Metallkontaktbereichen, wobei die Sekundärkontaktbereiche voneinander getrennt sind.

3. Verfahren nach Anspruch 1, dadurch gekennzeichnet, daß das Widerstandsbauelement einen diffundierten Widerstand umfaßt.

4. Verfahren nach Anspruch 1, dadurch gekennzeichnet, daß das Widerstandsbauelement einen Ionen-implantierten Widerstand umfaßt.

5. An einem Substrat ausgebildetes Widerstandsbauelement, gekennzeichnet durch einen ersten Metallkontaktbereich an einem Ende des Widerstandsbauelementes und einen zweiten Metallkontaktbereich an dem gegenüberliegenden Ende des Widerstandsbauelementes, wobei der erste und der zweite Metallkontaktbereich spiegelbildliche Spitzen haben, die aufeinander zu weisen, und wobei die Spitzen viel kleiner als die Größe des Metallkontaktbereiches sind, um die Bewegung eines Metallfadens von einer der Spitzen in Richtung der anderen zu erleichtern.

6. Widerstandsbauelement nach Anspruch 5, gekennzeichnet durch mehrere Sekundärmetallkontaktbereiche in dem Widerstandsbauelement zwischen dem ersten und dem zweiten Metallkontaktbereich.

7. Widerstandsbauelement nach Anspruch 5, dadurch gekennzeichnet, daß es einen Ionen-implantierten Widerstand umfaßt.

8. Widerstandsbauelement nach Anspruch 5, dadurch gekennzeichnet, daß es einen diffundierten Widerstand umfaßt.

Revendications

1. Procédé de réglage fin de la valeur d'un dispositif résistif situé à l'intérieur d'un circuit intégré, comprenant les étapes suivantes:

formation de régions de contact métallique au moins à chaque extrémité du dispositif résistif; chaque région de contact métallique ayant des extrémités ayant un poli-miroir tournées l'une vers l'autre, lesquelles extrémités sont bien plus petites que la taille de la région de contact métallique pour faciliter la migration du métal de l'une desdites extrémités vers l'autre,

établissement d'un courant électrique par impulsions qui circule à travers ledit dispositif résistif dans une seule direction uniquement, ledit courant électrique étant suffisant pour amener un filament métallique à migrer depuis l'une desdites extrémités de ladite région de contact métallique vers l'autre région de contact métallique, et interruption dudit courant électrique au bout d'une durée prédéterminée.

2. Procédé selon la revendication 1, qui comprend en outre la formation d'une pluralité de régions de contact secondaire dans le dispositif résistif entre lesdites régions de contact métallique, lesdites régions de contact secondaire étant séparées les unes des autres.

3. Procédé selon la revendication 1, dans lequel ledit dispositif résistif comprend une résistance diffusée.

4. Procédé selon la revendication 1, dans lequel ledit dispositif résistif comprend une résistance à implantation ionique.

5. Dispositif résistif formé sur un substrat, comprenant:

une première région de contact métallique à une extrémité dudit dispositif résistif, et

une seconde région de contact métallique à une extrémité opposée dudit dispositif résistif, lesdites première et deuxième régions de contact métallique ayant des extrémités présentant un poli-miroir tournées l'une vers l'autre, lesquelles extrémités sont bien plus petites que la taille de la région de contact métallique pour faciliter le mouvement d'un filament de métal depuis l'une desdites extrémités vers l'autre.

6. Dispositif résistif selon la revendication 5, comprenant une pluralité de régions de contact métallique secondaire à l'intérieur du dispositif résistif entre lesdites première et seconde régions de contact métallique.

7. Dispositif résistif selon la revendication 5, comprenant une résistance à implantation ionique.

8. Dispositif résistif selon la revendication 5, comprenant une résistance diffusée.